

☆TDK Multilayer Ceramic Chip Capacitors

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Creation Date: July 21, 2014

C3225X7R2A334M200AA (TDK item description : C3225X7R2A334MT****)

Applications



Commercial Grade



Please refer to Part No. CGA6M2X7R2A334M200AA for automotive use.

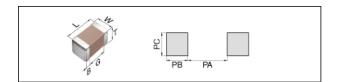
Feature

Mid

Mid Voltage (100 to 630V)

Series

C3225 [EIA CC1210]











Size	
Length(L)	3.20mm +/-0.40mm
Width(W)	2.50mm +/-0.30mm
Thickness(T)	2.00mm +/-0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern(PA)	2.00 to 2.40mm
Recommended Land Pattern(PB)	1.00 to 1.20mm
Recommended Land Pattern(PC)	1.90 to 2.50mm
Recommended Slit Pattern(SD)	

Electrical Characteristics	
Capacitance	330nF +/-20%
Rated Voltage	100Vdc
Temperature Characteristic	X7R(+/-15%)
Dissipation Factor	3% Max.
Insulation Resistance	1515MΩ Min.

Other	
Soldering Method	Reflow
AEC Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000Pcs Min.

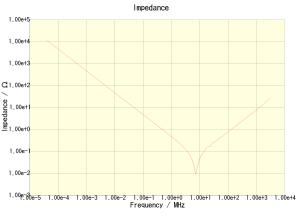
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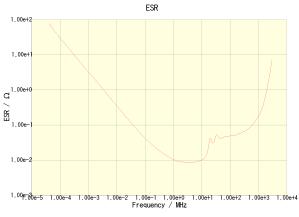
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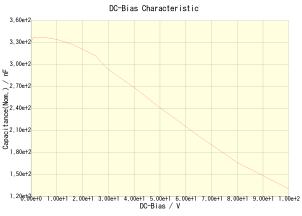
Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



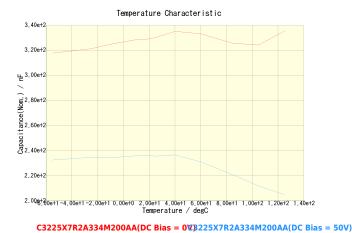


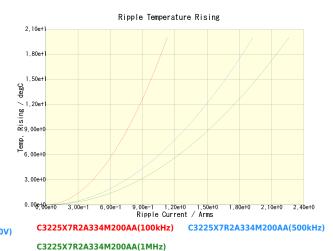
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